

Listing of Claims:

Claims 1-25 (Canceled)

Claim 26: (New) A method of making electrical connections between at least one first electronic component and a second electronic component, comprising:

fabricating a plurality of spring contact elements directly upon said at least one first electronic component, said spring contact elements each having a tip end which is spaced above a surface of the at least one first electronic component and at least one of said spring contact elements being a different size than the other spring contact elements; and

bringing the at least one first electronic component together with a second electronic component so that the tip ends of the spring contact elements are in electrical contact with corresponding terminals on the second electronic component.

Claim 27: (New) The method according to claim 26, wherein:

the at least one first electronic component is at least one active semiconductor device; and

the second electronic component is a test substrate; further comprising:

powering up the active semiconductor device while maintaining the tip ends of the spring contacts in electrical contact with the terminals of the second electronic component.

Claim 28 (New): A method of making electrical connections between at least one first electronic component and a second electronic component having terminals, comprising:

fabricating a first plurality of spring contact elements disposed in a first predetermined pattern directly upon said at least one first electronic component,

fabricating a second plurality of spring contact elements disposed in a second predetermined pattern directly upon said at least one first electronic component,

wherein,

each of said first plurality of spring contact elements and each of said second plurality of spring contact elements comprises a base and a contact tip, said base secured to said electronic component, said contact tip disposed in a first position

that is horizontally and vertically, with respect to said electronic component, displaced from said base, said contact tip being moveable out of said first position upon application of a first force on said contact tip, each of said first plurality of spring contact elements and each of said second plurality of spring contacts being sufficiently resilient to return substantially to said first position upon removal of said first force, and the first plurality of spring contact elements are of a different size than the second plurality of spring contact elements; and

bringing the at least one first electronic component together with a second electronic component so that the tip ends of the spring contact elements are in electrical contact with corresponding terminals on the second electronic component.